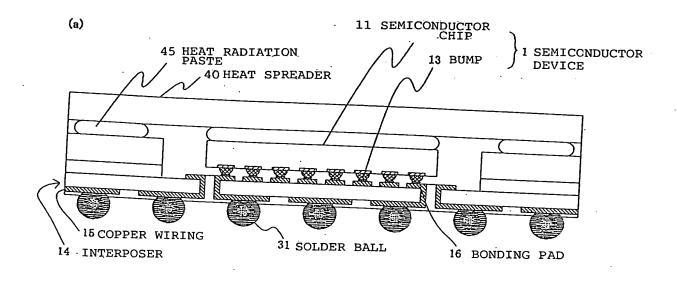
Fig. 1 Prior Art



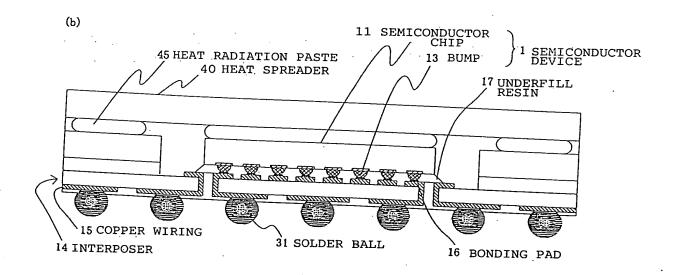


Fig. 2 Prior Art

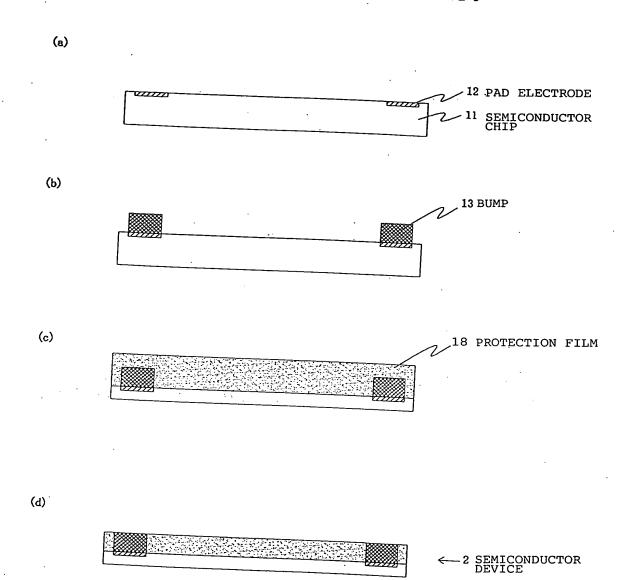


Fig. 3 Prior Art

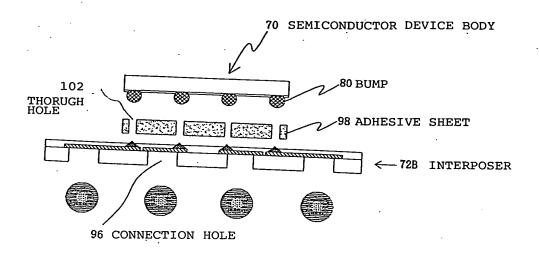
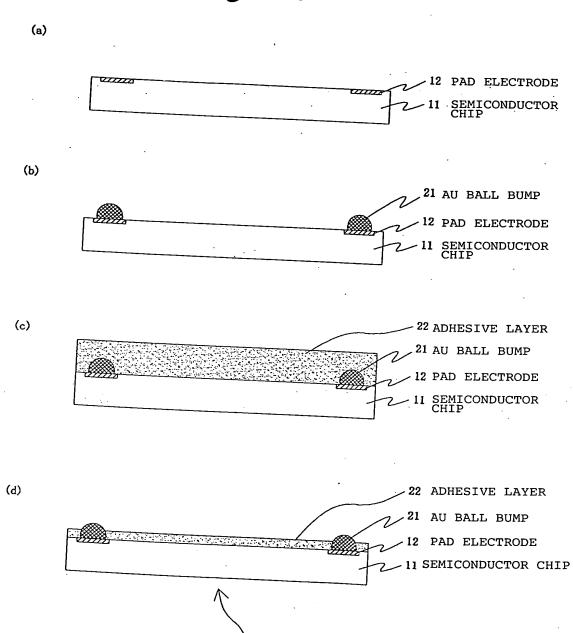


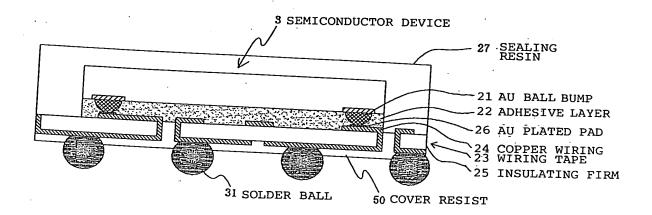
Fig. 4



3 SEMICONDUCTOR DEVICE

Fig. 5

(a)



(b)

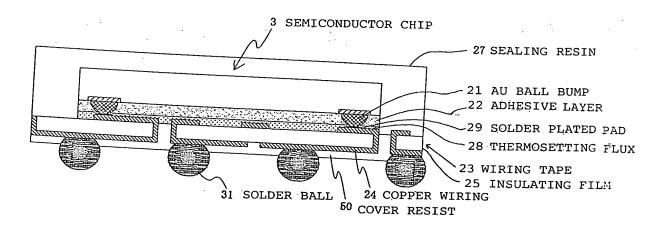


Fig. 6

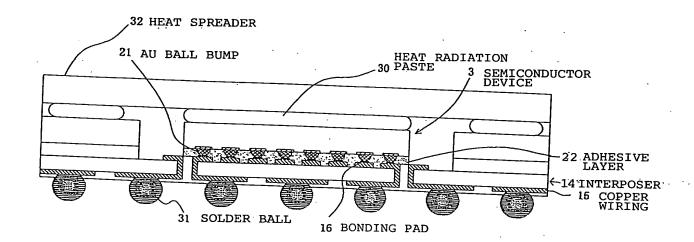


Fig. 7

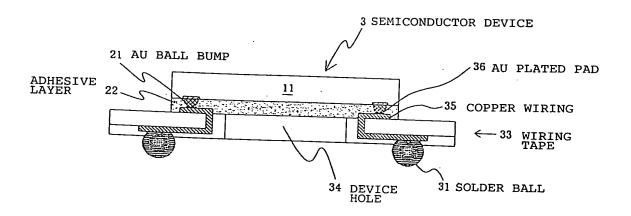
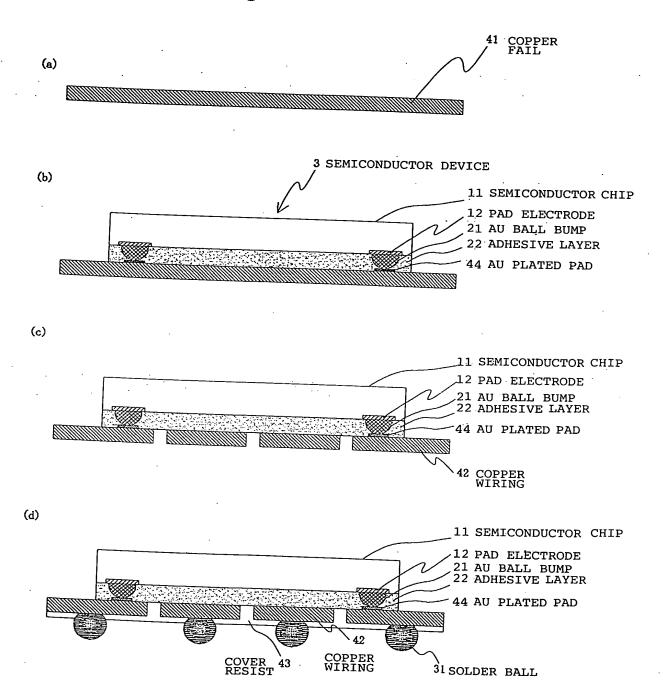
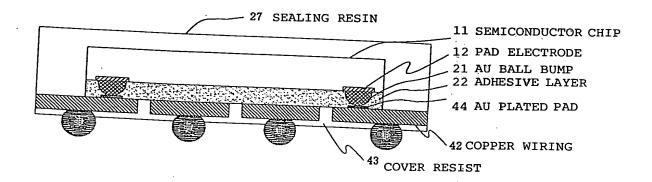


Fig. 8



(a)

Fig. 9



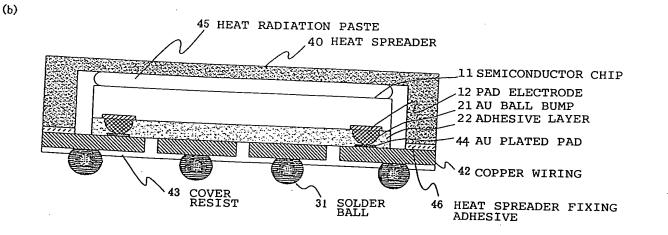


Fig. 10

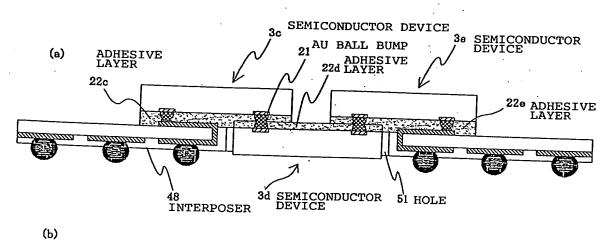
(a)

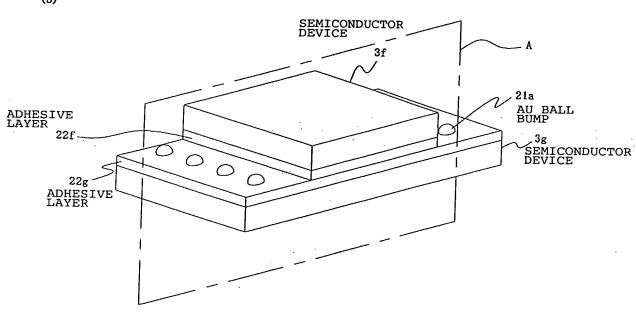
11 SEMICONDUCTOR CHIP 12 PAD ELECTRODE
21 AU BALL BUMP
22 ADHESIVE LAYER -44:AU PLATED PAD 42 COPPER WIRING 31 SOLDER BALL 43 COVER RESIST

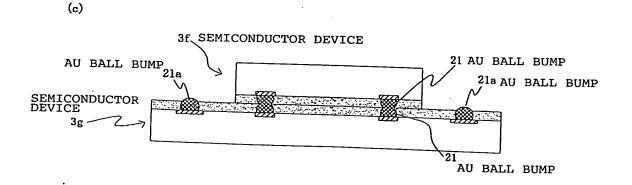
11 SEMICONDUCTOR CHIP 12 PAD ELECTRODE
21 AU BALL BUMP
22 ADHESIVE LAYER
44 AU PLATED PAD 142 COPPER WIRING 47 SEALING RESIN 31 SOLDER BALL

3

Fig. 11







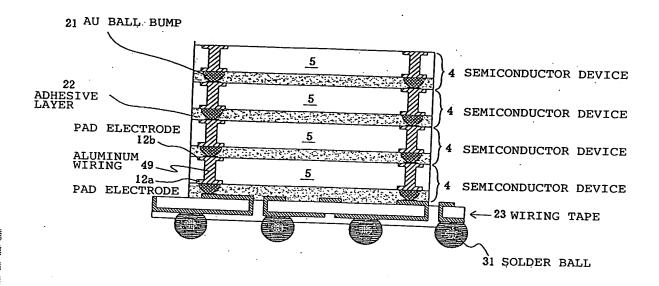


Fig.

